

Abstract of the Disclosure

A method of manufacturing a semiconductor laser chip has following steps. First, a semiconductor substrate including an active layer and a block layer is provided. An electrode line pattern and a marker are formed on the semiconductor substrate. The semiconductor substrate is etched to form a W channel. Then, an oxide layer is formed on the semiconductor substrate to cover the electrode line pattern and the marker. A part of the oxide layer is removed to form an electrode contact that exposes the electrode line pattern. A mounting electrode is formed on the electrode line pattern. Finally, the semiconductor substrate is divided into a plurality of semiconductor laser chip.